

IN THE SPECIFICATION:

Please amend the Specification as follows:

In the paragraph beginning at page 7, line 6:

Then, a resist pattern (not shown) of wirings and pads is formed on the metal film, and then the metal film in regions that are not covered with the resist pattern is removed by the sputter etching. Thus, an island-like first conductive pattern 2 is formed at one corner positioned near one end of the major surface of the ceramic carrier 1, and also an L-shaped second conductive pattern 3, on which the laser chip is mounted, is formed at a distance around the first conductive pattern 2. Also, a third conductive pattern 4 and a fourth conductive pattern 5, which extend while bending zigzag along both sides of the ceramic carrier 1, are formed at a distance in the region near the other end of the major surface of the ceramic carrier 1. End portions of the third and fourth conductive patterns 4, 5 positioned near the other end of the ceramic carrier 1 are formed as wire-bonding portions for locating wire-bonding points. Also, ~~bended~~ portions 4a, 5a in the middle of the third and fourth conductive patterns 4, 5, which are directed in a path having bends, are portions having the low thermal conductivity and have a pattern width that is narrower than that of both ~~ends~~ end portions.

In the paragraph beginning at page 8, line 7:

In turn, as shown in FIG.3, the sintered film is patterned by the photolithography method such that such sintered film remains in ~~regions~~ a temperature sensing resistive element portion of the third and fourth conductive patterns 4, 5 that are located on one end portion of the conductive patterns

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near the center of the ceramic carrier 1 and between the third and fourth conductive patterns 4, 5.

Thus, a thermistor element 6 made of the sintered film (temperature- sensing resistor film) whose both ends are connected to the third and fourth conductive patterns 4, 5 respectively is formed monolithically on the major surface of the ceramic carrier 1. Accordingly, a thermistor carrier having a laser chip mounting region (semiconductor element mounting portion) can be completed.